

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) A slurry for polishing copper-based metal containing a silica polishing material, an oxidizing agent, an amino acid, a triazole-based compound and water, wherein a content ratio of said amino acid to said triazole-based compound (amino acid / triazole-based compound (weight ratio)) is 5 to 8, wherein,

said amino acid is glycine,

said triazole-based compound is one of 1, 2, 3-triazole, 1, 2, 4-triazole and their derivatives thereof,

a content of said triazole-based compound is not less than 0.05% by weight and not greater than 0.5% by weight, and

a pH value of said slurry is in a range of 5 to 7.

2. (canceled)

3. (original) The slurry for polishing copper-based metal according to Claim 1, wherein said triazole-based compound is 1, 2, 4-triazole or its derivative.

4-5. (canceled)

6. (original) The slurry for polishing copper-based metal according to Claim 1, wherein said silica polishing material is colloidal silica.